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Atty. Docket No. CPAC.1001-1  
Appl. No. 09/802,443

No. 0196

P. 4

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Rajendra D. PENDSE, *et al.*

Application No.: 09/802,443

Filed: March 9, 2001

Title: Flip chip-in-leadframe package and  
process

Examiner: Victor V. Yevsikov

Group Art Unit: 2825

Date: May 2, 2003

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to  
Examiner Yevsikov in the United States Patent and Trademark Office, at  
fax no. 703 746-4117 on May 2, 2003.

Signed

Linda Shaw

COMMISSIONER FOR PATENTS  
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Alexandria, VA 22313-1450

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AMENDMENT

TECHNOLOGY CENTER 2800

Dear Sir:

Responsive to the Office action mailed December 4, 2002, kindly amend the application as  
follows:

Amendments to the claims are reflected in the Listing of Claims which begins on page 2 of this  
paper.

Remarks begin on page 5 of this paper.